

WAFER PROCESSING METHOD

ABSTRACT

A wafer processing method includes a height recording step of holding a wafer on a chuck table in the condition where a protective member attached to the front side of a functional layer is in contact with the chuck table, detecting the height of the back side of the wafer held on the chuck table in a Z direction in an area corresponding to each division line as moving the chuck table in an X direction, and recording an X coordinate on each division line and a Z coordinate corresponding to the X coordinate, and a cut groove forming step of positioning a cutting blade on the back side of the substrate of the wafer in the area corresponding to each division line and then moving the cutting blade in the Z direction according to the X coordinate and the Z coordinate recorded in the height recording step as moving the chuck table in the X direction to thereby form a cut groove having a depth not reaching the functional layer with a part of the substrate left between the bottom of the cut groove and the functional layer.

(Figure 5A)